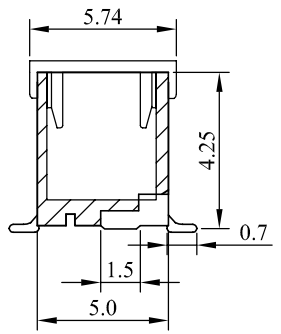
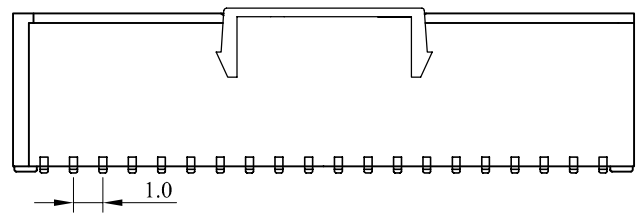


RECOMMENDED P.C. BOARD PATTERN DIM.



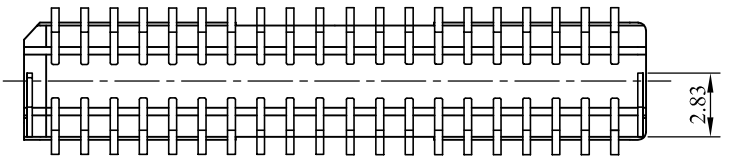
**Specifications**

**Electrical**

- Voltage Rating: 50VAC DC
- Current Rating: 1.0A AC DC
- Contact Resistance: Initial value/20mΩmax  
After environmental testing/40mΩmax
- Insulation Resistance: 100MΩmin
- Temperature Range: -25°C~+85°C
- Withstanding voltage:500V AC/minute

**Material and Finish**

- Header contact:Phosphor bronze,nickel-undercoated, tin-plated or gold-plated
- Water:Glass-filled polyamide,UL94V-0,natural(ivory)
- Solder tab:Brass,copper-undercoated,tin/lead-plated



SHD-V<sub>x</sub>-xx-LF  
LEADFREE  
BLANK:TIN/PLATED  
G:GOLD/PLATED

Circuits	Dimension mm (in.)		Part No.	Note
	A	B		
2*10	9.0(.354)	12.3(.484)	SHD-V <sub>x</sub> -20	
2*15	14.0(.551)	17.3(.681)	SHD-V <sub>x</sub> -30	
2*20	19.0(.748)	22.3(.878)	SHD-V <sub>x</sub> -40	
2*25	24.0(.945)	27.3(1.075)	SHD-V <sub>x</sub> -50	

	PART NO. SHD-V <sub>x</sub> -xx		CHECKED BY CY	TOLERANCES ARE .X ± 0.2 .XX ± .XXX ± AWG	DESCRIP TION: SHD 1.0mm Wire to Board Wafer SMT 180W(雙排無柱)		
	DWG NO. SHD-V <sub>x</sub> -xx					DRAWING BY	
	FILE NO.		PROJECTION	AREA	REVISIONS	HK	DATE
	UNIT / mm	SCALE 1:1					